L Number	Hits	Search Text	DB	Time stamp
1	6	"6180995"	USPAT;	2004/09/07 07:02
-			US-PGPUB;	
			EPO; JPO	
2	9	"6307247"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
			EPO; JPO	
3	13	"6287979"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
4	16	 "4634494"	EPO; JPO USPAT;	2004/09/07 07:03
*	10	"4034434"	US-PGPUB;	2004/09/07 07:03
			EPO; JPO	
5	19	"5742091"	USPAT;	2004/09/07 07:03
	_		US-PGPUB;	
			EPO; JPO	
6	16	"6303423"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
			EPO; JPO	
7	72	"6180995" "6307247" "6287979" "4634494"	USPAT;	2004/09/07 07:04
		"5742091" "6303423"	US-PGPUB;	
8	39	inductor and (oxide adj layer) and	EPO; JPO	2004/00/07 07:15
	39	("low-k" adj dielectric)	USPAT; US-PGPUB;	2004/09/07 07:15
		1 100 % day distriction	EPO; JPO	
10	3	(inductor and (oxide adj layer) and	USPAT;	2004/09/07 07:15
		("low-k" adj dielectric)) and (air adj	US-PGPUB;	,,,,,,,,, -
		gap)	EPO; JPO	
9	39	(inductor and (oxide adj layer) and	USPAT;	2004/09/07 07:06
		("low-k" adj dielectric)) and (method	US-PGPUB;	
		process)	EPO; JPO	
11	120	inductor and oxide and ("low-k" near1	USPAT;	2004/09/07 07:15
		(insulation dielectric))	US-PGPUB;	
12	17	(inductor and oxide and ("low-k" nearl	EPO; JPO USPAT;	2004/09/07 07:15
	1/	(insulation dielectric))) and (air adj	US-PGPUB;	2004/03/0/ 0/:15
		qap)	EPO; JPO	
13	o	inductor and (oxide with ("low-k" nearl	USPAT;	2004/09/07 07:17
	, i	(insulation dielectric)) with (air adj	US-PGPUB;	
		gap))	EPO; JPO	
14	0	inductor and (oxide with "low-k" with	USPAT;	2004/09/07 07:18
	,	(air adj gap))	US-PGPUB;	
1	_	industry and family massed lasters and	EPO; JPO	0004/00/05 05 55
15	0	inductor and (oxide near1 layer) and ("low-k" with (air adj gap))	USPAT;	2004/09/07 07:19
		(10m-v with (all ad) gap!)	US-PGPUB; EPO; JPO	
16	31	inductor and (oxide nearl layer) and	USPAT;	2004/09/07 07:19
		(("low-k" dielectric) with (air adj gap))	US-PGPUB;	= = = =
			EPO; JPO	
17	0	6495903.URPN.	USPAT	2004/09/07 07:23
18	8	("5539241" "5831331" "6153489"	USPAT	2004/09/07 07:23
		"6180433" "6221727" "6242791"		
		"6274920" "6287931").PN.		
19	67		USPAT;	2004/09/07 08:19
	:	"5742091" "6303423") not ((inductor and	US-PGPUB;	
		<pre>(oxide adj layer) and ("low-k" adj dielectric)) and (method process)) not</pre>	EPO; JPO	
		((inductor and oxide and ("low-k" near1		
		(insulation dielectric))) and (air adj		
		gap)) not (inductor and (oxide near1		
		layer) and (("low-k" dielectric) with (air		
		adj gap)))		
20	17	"6413827"	USPAT;	2004/09/07 08:19
			US-PGPUB;	
	_	6412000	EPO; JPO	
21	0	6413827.pn. and inductor	USPAT;	2004/09/07 08:20
			US-PGPUB;	
22	О	"sc12765tp"	EPO; JPO USPAT;	2004/09/07 09:30
	Ĭ		US-PGPUB;	2004/03/0/ 09:30
			EPO; JPO	

Cemiconductor adj fabrication adj US-PGPUB; PFO; JFO USPAT; US-PGPUB; PFO; JFO U		γ		,	, , , , , , , , , , , , , , , , , , ,
24 8564763 process	23	14			2004/09/07 09:37
24				1	
US -6, 472, 325 B1				EPO; JPO	
US -6,465,372 B1 US -6,465,433 B1 US -6,434,440,878 B1 US -6,334,913 B1 US -6,334,407 B1 US -6,331,210 B1 US -6,331,210 B1 US -6,331,704 B1 US -6,133,512 25	24	8564763	US -6,486,061 B1	USPAT;	2004/09/07 09:38
US -6,443,81 US -6,435,443 B1 US -6,485,443 B1 US -6,483,913 B1 US -6,483,913 B1 US -6,383,913 B1 US -6,383,913 B1 US -6,383,913 B1 US -6,393,525 B1 US -6,197,704 B1 US -6,197,704 B1 US -6,197,704 B1 US -6,197,704 B1 US -6,153,512 US -6,153			US -6,472,325 B1	US-PGPUB;	ľ
US -6,440,878 B1 US -6,383,913 B1 US -6,383,913 B1 US -6,338,913 B1 US -6,338,913 B1 US -6,331,220 B1 US -6,331,525 B1 US -6,153,512 25]	US -6,465,372 B1	EPO; JPO	
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US -6,348,407 B1 US -6,331,420 B1 US -6,331,420 B1 US -6,197,704 B1 US -6,197,04 B1 US -7,197 US	ĺ				
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US -6,303,525 B1					
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25			US -6,197,704 B1		
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6465372.pn. 6460878.pn. 63383913.pn. 6338407.pn. 6331420.pn. 6137704.pn. 6135152.pn. 6153512.pn. 6153512.pn. 6197704.pn. 6131420.pn. 6153512.pn. 6197704.pn. 6197704.pn. 6197704.pn. 6197704.pn. 6197704.pn. 619704.pn. 6197	25	11	6486061.pn.	USPAT;	2004/09/07 09:47
6455443.pn. 6440878.pn. 6383913.pn. 638407.pn. 63331420.pn. 6303525.pn. 6153512.pn. 6153512.pn. (substrate wafer) with (second near2 (low adj k)) with void with polish\$3 27	ľ		6472325.pn.	US-PGPUB;	
6455443.pn. 6440878.pn. 6383913.pn. 638407.pn. 63331420.pn. 6303525.pn. 6153512.pn. 6153512.pn. (substrate wafer) with (second near2 (low adj k)) with void with polish\$3 27			6465372.pn.	EPO: JPO	
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6384407.pn. 6331420.pn. 6303525.pn. 6197704.pn. 6193712.pn. 0 (substrate wafer) with (second near2 (low adj k)) with void with polish\$3 27					
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Carrell					
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26		1		1	1
adj k)) with void with polish\$3 1 (substrate wafer) with (low adj "k") with void with polish\$3 28		1	6153512.pn.		1
adj k) with void with polish\$3	26	0 '	(substrate wafer) with (second near2 (low	USPAT;	2004/09/07 09:50
1 (substrate wafer) with (low adj "k") with void with polish\$3 28 1 (substrate wafer) with (low adj "k") with (void (via adj hole)) with polish\$3 29 11 (substrate wafer) with (low adj "k") with (void via hole) with polish\$3 30 8 ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3 30 8 ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd ((substrate wafer) with (low adj "k") USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPU				1	' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '
27		·	,, <u>p</u> 00	1	
void with polish\$3	27	1 1	(substrate wafer) with (low add k) with	1 '	2004/09/07 09:53
28	2'	+ '		· ·	2004/09/07 09:52
1 (substrate wafer) with (low adj "k") with (void (via adj hole)) with polish\$3 (US-PGPUB; EPG; JPO) 29	i	!	void with polish\$3	1	
(void (via adj hole)) with polish\$3		_ '		1	l
29	28	1		1	2004/09/07 09:52
29			(void (via adj hole)) with polish\$3	US-PGPUB;	
(void via hole) with polish\$3 8 ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd 8 (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd 8 (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd 10 cvd) and cmp 10 cvd) and cmp 11 cvd) and cmp 12 cvd) and cmp 13 cvd) and cmp 14 cvd) and cmp 15 cvd) and cmp 16 cvd) and cmp 17 cvd) and cmp 18 cvd) and cmp 19 cvd) and cmp 10 cvd)	ĺ			EPO; JPO	
(void via hole) with polish\$3	29	11	(substrate wafer) with (low adj "k") with	USPAT:	2004/09/07 10:10
8 ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd USPAT; US-PGPUB; EPO; JPO (((substrate wafer) with (low adj "k") USPAT; US-PGPUB; Cvd) and cmp USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO;					, ,
8 ((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd 8 (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd 8 (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd) uspAT; us-PGPUB; EPO; JPO uspAT; us-PGPUB; us-P		· '	(· · · · · · · · · · · · · · · · · · ·	1	
(void via hole) with polish\$3) and cvd (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd US-PGPUB; EPO; JPO USPAT; 2004/09/07 10 USPAT; 2004/09/07 10 USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB;	30	ا ۾ ا	((substrate wafer) with (low adi "k") with	1	2004/09/07 10:11
31 8 (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd) and cmp (US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT	"			1	2004/03/07 10:11
8 (((substrate wafer) with (low adj "k") with (void via hole) with polish\$3) and cvd) and cmp 32 2 "5912187"			(Void Via Hote) with polish\$3) and eva	1	
with (void via hole) with polish\$3) and cvd) and cmp "5912187" "6322714" "6322714" "6322714" "6352934" "6352934" "6458646" 36 4 "6458646" 37 0 ("5912187" "6322714" "6352934" "6399432" "6399432" USPAT; US-PGPUB; EPO; JPO			(//- 3		
Cvd) and cmp	31	8		l -	2004/09/07 10:24
32 2 "5912187" USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; UNDOPED WITH US-PGPUB; UNDOPED		i		1	
US-PGPUB; EPO; JPO USPAT; US-PGPUB; UNS-PGPUB;			cvd) and cmp	EPO; JPO	
EPO; JPO USPAT; US-PGPUB;	32	2	"5912187"	USPAT;	2004/09/07 10:24
EPO; JPO USPAT; US-PGPUB;		1		-	1
33 7 "6322714" USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; UNDOPED WITH US-PGPUB;		1		· · · · · · · · · · · · · · · · · · ·	1
US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; US-PGPUB; EPO; JPO USPAT; US-PGPUB; US	l 33	7	"6322714"		2004/09/07 10:24
### BEPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; USPAT; USP		, ,	· · · · · · · · · · · · · · · · · · ·		
34 3 "6352934" USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; USPAT; US-PGPUB; US					1
US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO US-PGPUB; EPO; JPO US-PGPUB; EPO; JPO US-PGPUB; US-PGPU	124	_ !	1162520241	•	2004/00/07 55 55
EPO; JPO USPAT; US-PGPUB; UNDOped with etch\$3) EPO; JPO USPAT; US-PGPUB; UNDOped with etch\$3) US-PGPUB; UNDOped with etch\$3) USPAT; USPAT; US-PGPUB; UNDOped with etch\$3) USPAT; USPAT; USPAT; US-PGPUB; UNDOped with etch\$3)	34	ا د	"OJD2734"		2004/09/07 10:24
35 6 "6399432" USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; Undoped with etch\$3) 37 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10					1
US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; USPAT; US-PGPUB; EPO; JPO US-PGPUB; undoped with etch\$3) 20 "5912187" "6322714" "6352934" "6399432" USPAT; USPAT; US-PGPUB; US-PG		1		EPO; JPO	1
36 4 "6458646" US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO US-PGPUB; EPO; JPO USPAT; USPAT; US-PGPUB; EPO; JPO US-PGPUB; US-PGPUB; undoped with etch\$3) 37 20 "5912187" "6332714" "6352934" "6399432" USPAT; 2004/09/07 10	35	6	"6399432"	USPAT;	2004/09/07 10:24
BPO; JPO USPAT; 2004/09/07 10 USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT; US-PGPUB; EPO; JPO USPAT;				US-PGPUB;	
36 4 "6458646" USPAT; US-PGPUB; EPO; JPO 38 0 ("5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10 "6458646") and ((local\$2 adj doped) with US-PGPUB; undoped with etch\$3) 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10					
US-PGPUB; EPO; JPO 0 ("5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10 "6458646") and ((local\$2 adj doped) with US-PGPUB; undoped with etch\$3) 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10	36	4	"6458646"		2004/09/07 10:24
EPO; JPO ("5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10 "6458646") and ((local\$2 adj doped) with US-PGPUB; undoped with etch\$3) 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10			1		2004,09,07 10:24
38 0 ("5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10 "6458646") and ((local\$2 adj doped) with US-PGPUB; undoped with etch\$3) 37 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10					
"6458646") and ((local\$2 adj doped) with US-PGPUB; undoped with etch\$3) EPO; JPO 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10	30		/#E010107# #C000714# #C00004# #C000:00#		0004/00/07 50 5
undoped with etch\$3) EPO; JPO 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10	30	ان		1	2004/09/07 10:34
37 20 "5912187" "6322714" "6352934" "6399432" USPAT; 2004/09/07 10				· · · · · · · · · · · · · · · · · · ·	
	37	20	"5912187" "6322714" "6352934" "6399432"	USPAT;	2004/09/07 10:39
EPO; JPO				1	
	39		6399432 JIRPN		2004/09/07 10:42
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"5529197" "5629544" "5652172"				55171	2004/09/07 10:43
			!!!		
"5654570" "5677563" "5718800"					
"5739066" "5789295" "5827747"				İ	
"5830789" "5831313" "5956584").PN.			"5830789" "5831313" "5956584").PN.	<u> </u>	<u> </u>